### (19) World Intellectual Property Organization

International Bureau





## (43) International Publication Date 20 October 2005 (20.10.2005)

### **PCT**

# (10) International Publication Number WO 2005/096751 A2

(51) International Patent Classification: Not classified

(21) International Application Number:

PCT/US2005/011021

(22) International Filing Date: 1 April 2005 (01.04.2005)

(25) Filing Language: English

(26) Publication Language: English

(**30**) **Priority Data:** 60/559,140

2 April 2004 (02.04.2004) US

(71) Applicant (for all designated States except US): EKSI-GENT TECHNOLOGIES LLC [US/US]; 2021 La Positas Court, Suite 161, Livermore, CA 94550 (US).

(72) Inventors; and

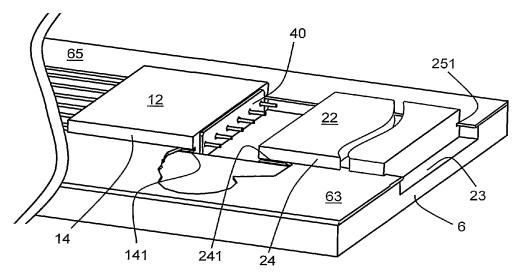
(75) Inventors/Applicants (for US only): ARNOLD, Don, W. [US/US]; 17461 Old Tower Road, Livermore, CA 94550 (US). HENCKEN, Kenneth, R. [US/US]; 2665 Calle Alegre, Pleasanton, CA 94566 (US). DATWANI, Sammy, S. [GB/US]; 6450 Dougherty Road, Apt #634, Dublin, CA 94568 (US). LEUNG, Patrick, Pak-Ho [CN/US]; 1060 Furlong Street, Belmont, CA 94002 (US). CYR, Douglas,

R. [CA/US]; 608 Via Del Sol, Livermore, CA 94550 (US). REHM, Jason, E. [US/US]; 1211 Regent Street, Alameda, CA 94501 (US).

- (74) Agents: SHELDON, Jeffrey, G.\_ et al.; Sheldon & Mak, 225 South Lake Avenue, Suite 900, Pasadena, CA 91101 (US).
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

[Continued on next page]

(54) Title: MICROFLUIDIC CONNECTIONS



(57) Abstract: A junction is made between a first microfluidic substrate (12) having an elongate component (303) protruding from it and a second microfluidic substrate (22) having a corresponding conduit (261). Each of the substrates has a pair of alignment features, for example planar orthogonal surfaces (13,15; 23,25) or grooves (141,151; 241, 251) in opposite sides of the substrate. The substrates are placed on an alignment jig 6 having location features (63, 65) corresponding to the alignment features. The elongate component can be surrounded by a compressible gasket 40). The substrates are pushed towards each other so that the elongate component enters the conduit and the gasket, if any, is compressed. A fluid-tight junction results so long as the substrates are maintained in the necessary position, either by permanent means, or, if a junction which can be disassembled is needed, by maintaining pressure between the substrates. Novel apparatus and novel microfluidic assemblies, including microfluidic chips having grooves in their sides, are described.

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FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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#### Published:

 without international search report and to be republished upon receipt of that report